IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bo				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material:					ials and Mf	ls and Mfg Information			
Supplie	r Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
nsemi												2025-05-11			
Contact N	lame		Title - Contact]	Phone - Contact*					Email - Contact*			
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufac		Manufactu	nufacturing Site Weight		Veight*	UOM	Unit Type	
		NOIP1SP0480A-STI		PYTHON480 1/3.6", BW_ CRA23.59		23.59	2025-05-11		,	TWU		3	8.3603	mg	Each
Ianufa	cturing Proccess Informat	tion							,						
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020		-STD-020 MSL	Rating	Peak Process		s Body Temperature Max Time at Peak		Temperatu	ire Num	ber of Reflow Cyc	eles	
	SnAgCu		CU Alloy 4				245		C	30		seconds 3			
omments	3														
or more	information regarding material	composition]	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.6894	mg	Supplier	Silicon (Si)	7440-21-3		6.6894	mg
Glass Attach Epoxy	0.0053	mg		Miscellaneous	trade secret		0.0007	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0046	mg
Glass Lid /Cap	29.3747	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		2.9375	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		1.4687	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		1.4687	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.9375	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		1.4687	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		19.0936	mg
Metal Shielding	0.0483	mg	Supplier	Copper (Cu)	7440-50-8		0.0002	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0481	mg
RDL	0.053	mg	В	Nickel (Ni)	7440-02-0		0.0328	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0001	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0198	mg
Solder Ball	2.1563	mg	Supplier	Silver (Ag)	7440-22-4		0.0647	mg
			Supplier	Tin (Sn)	7440-31-5		2.0808	mg
			Supplier	Copper (Cu)	7440-50-8		0.0108	mg
Substrate and Solder Mask	der Mask 0.0333	mg	Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0033	mg
			Supplier	9-Phenylacridine	602-56-2		0.0017	mg
			Supplier	2-Propenoic acid	1245638-61-2		0.0033	mg
			Supplier	3-Methoxy-1-butanol	2517-43-3		0.0083	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0083	mg
			Supplier	1-Methoxy-2-propyl acetate (MPA)	108-65-6		0.0083	mg